

## 32M x 64/72 Two-Bank Unbuffered SDRAM Module

### Features

- 168-Pin Unbuffered 8-Byte Dual In-Line Memory Module
- 32Mx64/72 Synchronous DRAM DIMM
- Two speed sorts:
  - -260 and -360 for PC100 applications
- Inputs and outputs are LVTTTL (3.3V) compatible
- Single 3.3V ± 0.3V Power Supply
- Single Pulsed RAS interface
- SDRAMs have 4 internal banks
- Module has 2 physical banks
- Fully Synchronous to positive Clock Edge
- Data Mask for Byte Read/Write control
- Auto Refresh (CBR) and Self Refresh
- Automatic and controlled Precharge commands
- Programmable Operation:
  - CAS Latency: 2, 3
  - Burst Type: Sequential or Interleave
  - Burst Length: 1, 2, 4, 8, Full-Page (Full-Page supports Sequential burst only)
  - Operation: Burst Read and Write or Multiple Burst Read with Single Write
- Suspend Mode and Power Down Mode
- 12/10/2 Addressing (Row/Column/Bank)
- 4096 Refresh cycles distributed across 64ms
- Serial Presence Detect
- Card size: 5.25" x 1.375" x 0.158" max
- Gold contacts
- SDRAMs in TSOP Type II Package

### Description

IBM13N32644JCA / IBM13N32734JCA are unbuffered 168-pin Synchronous DRAM Dual In-Line Memory Modules (DIMMs) which are organized as 32Mx64 and 32Mx72 high-speed memory arrays and are configured as two 16Mx64/72 physical banks. The DIMMs use sixteen (32Mx64) or eighteen (32Mx72) 16Mx8 SDRAMs in 400mil TSOP II packages. The DIMMs achieve high-speed data-transfer rates of up to 100MHz by employing a prefetch/pipeline hybrid architecture that supports the JEDEC 1N rule while allowing very low burst power.

The -260 and -360 speed sort DIMMs are compatible with the Intel PC100 SDRAM unbuffered DIMM specification.

All control, address, and data input/output circuits are synchronized with the positive edge of the externally supplied clock inputs.

All inputs are sampled at the positive edge of each externally supplied clock (CK0 - CK3). Internal operating modes are defined by combinations of RAS,

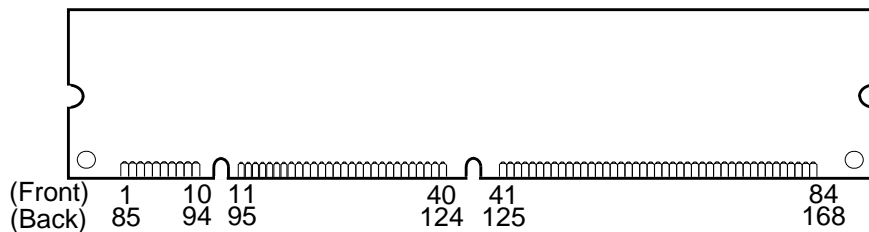
CAS, WE, S0-S3, DQMB, and CKE0-CKE1 signals. A command decoder initiates the necessary timings for each operation. A 14-bit address bus accepts address information in a row/column multiplexing arrangement.

Prior to any Access operation, the CAS latency, burst type, burst length, and burst operation type must be programmed into the DIMM by address inputs A0-A9 during the Mode Register Set cycle.

The DIMM uses serial presence detects implemented via a serial EEPROM using the two pin IIC protocol. The first 128 bytes of serial PD data are used by the DIMM manufacturer. The last 128 bytes are available to the customer.

All IBM 168-pin DIMMs provide a high-performance, flexible 8-byte interface in a 5.25" long space-saving footprint. Related products include both EDO DRAM and SDRAM unbuffered DIMMs in both non-parity x64 and ECC-Optimized x72 configurations.

### Card Outline





## Pin Description

CK0 - CK3	Clock Inputs	DQ0 - DQ63	Data Input/Output
CKE0 - CKE1	Clock Enables	CB0 - CB7	Check Bit Data Input/Output
$\overline{\text{RAS}}$	Row Address Strobe	DQMB0 - DQMB7	Data Mask
$\overline{\text{CAS}}$	Column Address Strobe	$V_{\text{DD}}$	Power (3.3V)
$\overline{\text{WE}}$	Write Enable	$V_{\text{SS}}$	Ground
$\overline{\text{S}}_0, \overline{\text{S}}_1, \overline{\text{S}}_2, \overline{\text{S}}_3$	Chip Selects	NC	No Connect
A0 - A9, A11	Address Inputs	SCL	Serial Presence Detect Clock Input
A10 /AP	Address Input/Autoprecharge	SDA	Serial Presence Detect Data Input/Output
BA0, BA1	SDRAM Bank Address Inputs	SA0-2	Serial Presence Detect Address Inputs
		WP	Serial Presence Detect Write Protect Input

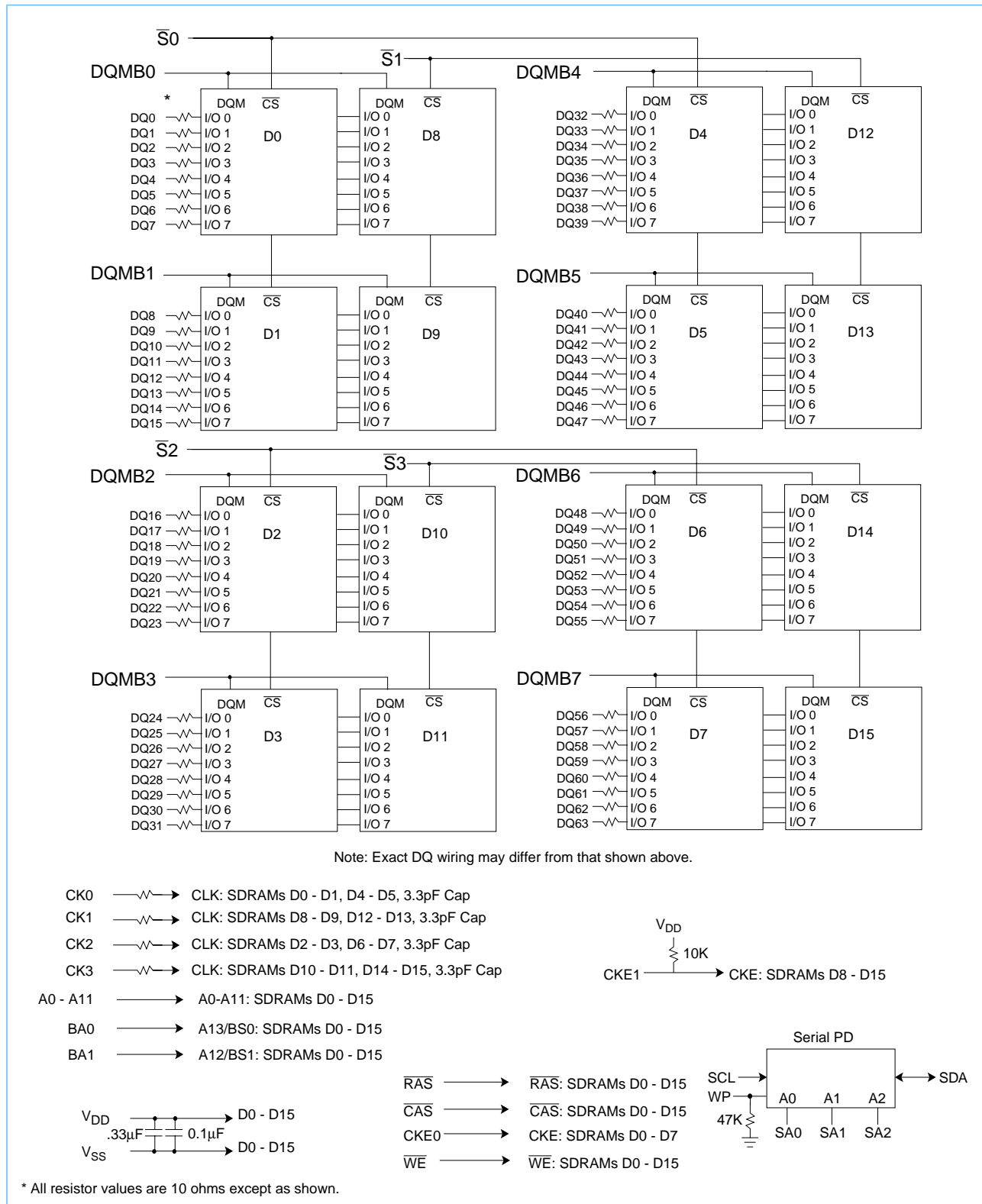
## Pinout

Pin#	Front Side	Pin#	Back Side	Pin#	Front Side	Pin#	Back Side	Pin#	Front Side	Pin#	Back Side	Pin#	Front Side	Pin#	Back Side
1	$V_{\text{SS}}$	85	$V_{\text{SS}}$	22	CB1	106	CB5	43	$V_{\text{SS}}$	127	$V_{\text{SS}}$	64	$V_{\text{SS}}$	148	$V_{\text{SS}}$
2	DQ0	86	DQ32	23	$V_{\text{SS}}$	107	$V_{\text{SS}}$	44	NC	128	CKE0	65	DQ21	149	DQ53
3	DQ1	87	DQ33	24	NC	108	NC	45	$\overline{\text{S}}_2$	129	$\overline{\text{S}}_3$	66	DQ22	150	DQ54
4	DQ2	88	DQ34	25	NC	109	NC	46	DQMB2	130	DQMB6	67	DQ23	151	DQ55
5	DQ3	89	DQ35	26	$V_{\text{DD}}$	110	$V_{\text{DD}}$	47	DQMB3	131	DQMB7	68	$V_{\text{SS}}$	152	$V_{\text{SS}}$
6	$V_{\text{DD}}$	90	$V_{\text{DD}}$	27	$\overline{\text{WE}}$	111	$\overline{\text{CAS}}$	48	NC	132	NC	69	DQ24	153	DQ56
7	DQ4	91	DQ36	28	DQMB0	112	DQMB4	49	$V_{\text{DD}}$	133	$V_{\text{DD}}$	70	DQ25	154	DQ57
8	DQ5	92	DQ37	29	DQMB1	113	DQMB5	50	NC	134	NC	71	DQ26	155	DQ58
9	DQ6	93	DQ38	30	$\overline{\text{S}}_0$	114	$\overline{\text{S}}_1$	51	NC	135	NC	72	DQ27	156	DQ59
10	DQ7	94	DQ39	31	NC	115	$\overline{\text{RAS}}$	52	CB2	136	CB6	73	$V_{\text{DD}}$	157	$V_{\text{DD}}$
11	DQ8	95	DQ40	32	$V_{\text{SS}}$	116	$V_{\text{SS}}$	53	CB3	137	CB7	74	DQ28	158	DQ60
12	$V_{\text{SS}}$	96	$V_{\text{SS}}$	33	A0	117	A1	54	$V_{\text{SS}}$	138	$V_{\text{SS}}$	75	DQ29	159	DQ61
13	DQ9	97	DQ41	34	A2	118	A3	55	DQ16	139	DQ48	76	DQ30	160	DQ62
14	DQ10	98	DQ42	35	A4	119	A5	56	DQ17	140	DQ49	77	DQ31	161	DQ63
15	DQ11	99	DQ43	36	A6	120	A7	57	DQ18	141	DQ50	78	$V_{\text{SS}}$	162	$V_{\text{SS}}$
16	DQ12	100	DQ44	37	A8	121	A9	58	DQ19	142	DQ51	79	CK2	163	CK3
17	DQ13	101	DQ45	38	A10/AP	122	BA0	59	$V_{\text{DD}}$	143	$V_{\text{DD}}$	80	NC	164	NC
18	$V_{\text{DD}}$	102	$V_{\text{DD}}$	39	BA1	123	A11	60	DQ20	144	DQ52	81	WP	165	SA0
19	DQ14	103	DQ46	40	$V_{\text{DD}}$	124	$V_{\text{DD}}$	61	NC	145	NC	82	SDA	166	SA1
20	DQ15	104	DQ47	41	$V_{\text{DD}}$	125	CK1	62	NC	146	NC	83	SCL	167	SA2
21	CB0	105	CB4	42	CK0	126	NC	63	*CKE1	147	NC	84	$V_{\text{DD}}$	168	$V_{\text{DD}}$

**Note:** All pin assignments are consistent for all 8-byte unbuffered versions. Check Bits (CB0 - CB7) are applicable only to the x72 DIMM; for the x64 DIMM these pins are no connects (NC). \* CKE1 is terminated with a 10k ohm pullup resistor.

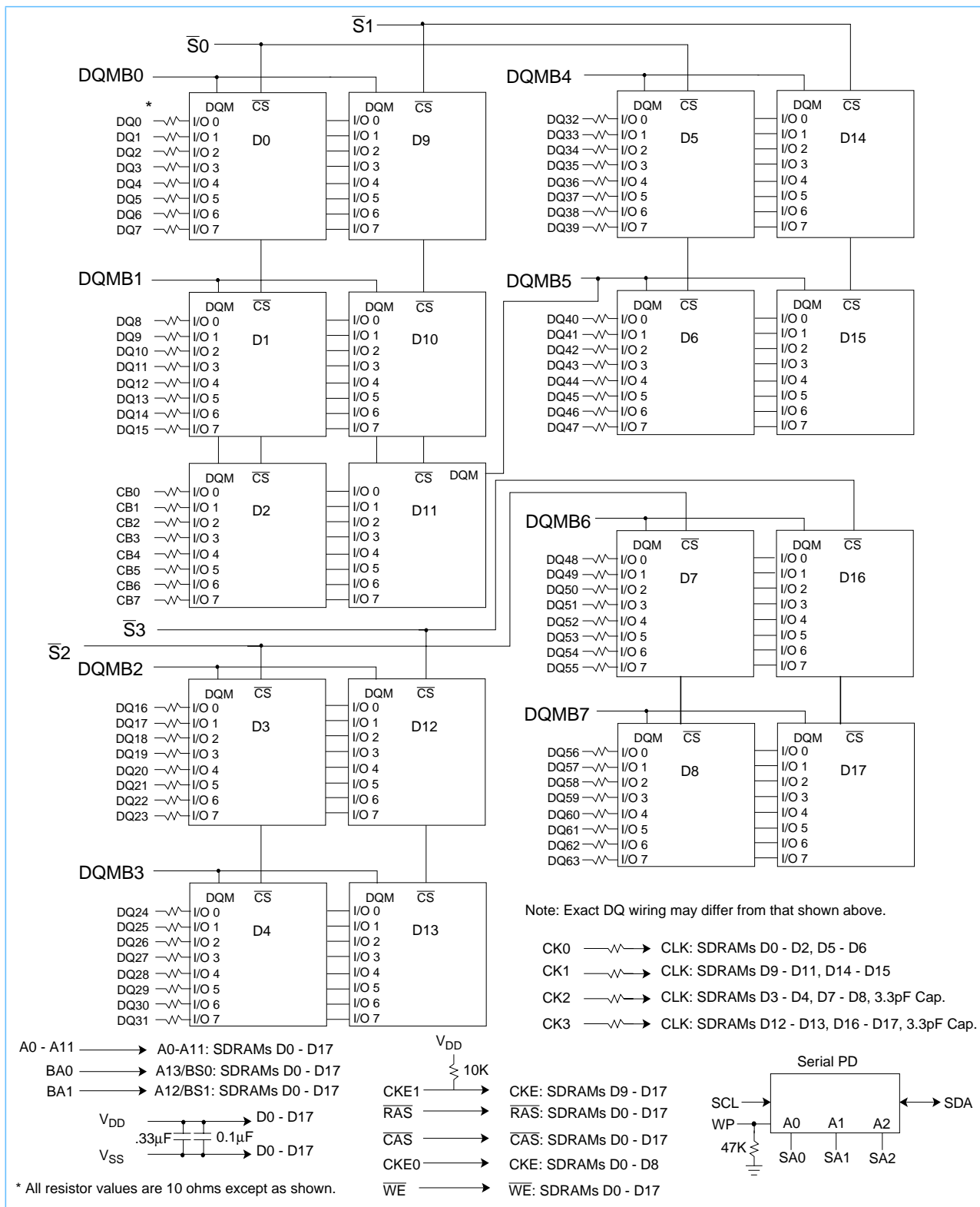
## Ordering Information

Part Number	Organization	Clock Cycle	Leads	Dimension	Power
IBM13N32644JCA-260T	16Mx64	10ns	Gold	5.25" x 1.375" x 0.158"	3.3V
IBM13N32644JCA-360T					
IBM13N32734JCA-260T	16Mx72				
IBM13N32734JCA-360T					

**32Mx64 SDRAM DIMM Block Diagram (2 Bank, 16Mx8 SDRAMs)**




### 32Mx72 SDRAM DIMM Block Diagram (2 Bank, 16Mx8 SDRAMs)





## Input/Output Functional Description

Symbol	Type	Signal	Polarity	Function
CK0 - CK3	Input	Pulse	Positive Edge	The system clock inputs. All of the SDRAM inputs are sampled on the rising edge of their associated clock.
CKE0, CKE1	Input	Level	Active High	Activates the SDRAM CLK signals when high and deactivates them when low. By deactivating the clocks, CKE0/CKE1 low initiates the Power Down mode, Suspend mode, or the Self Refresh mode.
$\overline{S0} - \overline{S3}$	Input	Pulse	Active Low	Enables the associated SDRAM command decoder when low and disables the command decoder when high. When the command decoder is disabled, new commands are ignored but previous operations continue.
$\overline{RAS}$ , $\overline{CAS}$ $\overline{WE}$	Input	Pulse	Active Low	When sampled at the positive rising edge of the clock, $\overline{CAS}$ , $\overline{RAS}$ , and $\overline{WE}$ define the operation to be executed by the SDRAM.
BA0, BA1	Input	Level	—	Selects which SDRAM bank is to be active.
A0 - A9 A10/AP A11	Input	Level	—	During a Bank Activate command cycle, A0-A11 defines the row address (RA0-RA11) when sampled at the rising clock edge. During a Read or Write command cycle, A0-A9 defines the column address (CA0-CA9) when sampled at the rising clock edge. In addition to the column address, AP is used to invoke Autoprecharge operation at the end of the Burst Read or Write cycle. If AP is high, autoprecharge is selected and BA0/BA1 define the bank to be precharged. If AP is low, autoprecharge is disabled. During a Precharge command cycle, AP is used in conjunction with BA0/BA1 to control which bank(s) to precharge. If AP is high all 4 banks will be precharged regardless of the state of BA0/BA1. If AP is low, then BA0/BA1 are used to define which bank to precharge.
DQ0 - DQ63, CB0 - CB7	Input Output	Level	—	Data and Check Bit Input/Output pins operate in the same manner as on conventional DRAMs.
DQMB0 - DQMB7	Input	Pulse	Active High	The Data Input/Output mask places the DQ buffers in a high impedance state when sampled high. In Read mode, DQM has a latency of two clock cycles and controls the output buffers like an output enable. In Write mode, DQM has a latency of zero and operates as a byte mask by allowing input data to be written if it is low but blocks the Write operation if DQM is high.
SA0 - SA2	Input	Level	—	Address inputs. Connected to either $V_{DD}$ or $V_{SS}$ on the system board to configure the Serial Presence Detect EEPROM address.
SDA	Input Output	Level	—	Serial Data. Bidirectional signal used to transfer data into and out of the Serial Presence Detect EEPROM. Since the SDA signal is Open Drain/Open Collector at the EEPROM, a pull-up resistor is required on the system board.
SCL	Input	Pulse	—	Serial Clock. Used to clock all Serial Presence Detect data into and out of the EEPROM. Since the SCL signal is inactive in the "high" state, a pull-up resistor is recommended on the system board.
WP	Input	Level	Active High	Hardware Write Protect. When WP is active, writing to the EEPROM array is inhibited. On the DIMM, this input is connected to the EEPROM Write Protect input and is also tied to ground through a 47K ohm pull-down resistor.
$V_{DD}$ , $V_{SS}$	Supply			Power and ground for the module.



## Serial Presence Detect (Part 1 of 2)

Byte #	Description	SPD Entry Value	Serial PD Data Entry (Hexadecimal)	Notes	
0	Number of Serial PD Bytes Written during Production	128	80		
1	Total Number of Bytes in Serial PD device	256	08		
2	Fundamental Memory Type	SDRAM	04		
3	Number of Row Addresses on Assembly	12	0C		
4	Number of Column Addresses on Assembly	9	0A		
5	Number of DIMM Banks	2	02		
6 - 7	Data Width of Assembly	32M x 64	x64	48	
		32M x 72	x72	00	
8	Voltage Interface Level of this Assembly	LVTTTL	01		
9	SDRAM Device Cycle Time at CL=3	10.0ns	A0		
10	SDRAM Device Access Time from Clock at CL=3	6.0ns	60	1	
11	DIMM Configuration Type	32M x 64	Non-Parity	00	
		32M x 72	ECC	02	
12	Refresh Rate/Type	SR/1x(15.625us)	80		
13	Primary SDRAM Device Width	x8	08		
14	Error Checking SDRAM Device Width	32M x 64	N/A	00	
		32M x 72	x8	08	
15	SDRAM Device Attr: Min Clk Delay, Random Col Access	1 Clock	01		
16	SDRAM Device Attributes: Burst Lengths Supported	1,2,4,8, Full Page	8F		
17	SDRAM Device Attributes: Number of Device Banks	4	04		
18	SDRAM Device Attributes: $\overline{CAS}$ Latencies Supported	2, 3	06		
19	SDRAM Device Attributes: $\overline{CS}$ Latency	0	01		
20	SDRAM Device Attributes: $\overline{WE}$ Latency	0	01		
21	SDRAM Module Attributes	Unbuffered	00		
22	SDRAM Device Attributes: General	Wr-1/Rd Burst, Precharge All, Auto-Precharge, $V_{DD} \pm 10\%$	0E		
23	Minimum Clock Cycle at CL=2	-260	10.0ns	A0	
		-360	15.0ns	F0	
24	Maximum Data Access Time ( $t_{AC}$ ) from Clock at CL=2	-260	6.0ns	60	1
		-360	9.0ns	90	
25	Minimum Clock Cycle Time at CL=1	N/A	00		
26	Maximum Data Access Time ( $t_{AC}$ ) from Clock at CL=1	N/A	00		
27	Minimum Row Precharge Time ( $t_{RP}$ )	20ns	14		
28	Minimum Row Active to Row Active delay ( $t_{RRD}$ )	20ns	14		

1. See the AC output load circuit in the AC Characteristics section below
2. cc = Checksum Data byte, 00-FF (Hex)
3. "R" = Alphanumeric revision code, A-Z, 0-9
4. rr = ASCII coded revision code byte "R"
5. yy = Binary coded decimal year code, 00-99 (Decimal) → 00-63 (Hex)
6. ww = Binary coded decimal week code, 01-52 (Decimal) → 01-34 (Hex)
7. ss = Serial number data byte, 00-FF (Hex)



## Serial Presence Detect (Part 2 of 2)

Byte #	Description	SPD Entry Value	Serial PD Data Entry (Hexadecimal)	Notes	
29	Minimum $\overline{RAS}$ to $\overline{CAS}$ delay ( $t_{RCD}$ )	20ns	14		
30	Minimum $\overline{RAS}$ Pulse width ( $t_{RAS}$ )	50ns	32		
31	Module Bank Density	128MB	20		
32	Address and Command Setup Time Before Clock	2.0ns	20		
33	Address and Command Hold Time After Clock	1.0ns	10		
34	Data Input Setup Time Before Clock	2.0ns	20		
35	Data Input Hold Time After Clock	1.0ns	10		
36 - 61	Reserved	Undefined	00		
62	SPD Revision	1.2A	12		
63	Checksum for bytes 0 - 62	Checksum Data	cc	2	
64 - 71	Manufacturers' JEDEC ID Code	IBM	A400000000000000		
72	Module Manufacturing Location	Toronto, Canada	91		
		Vimercate, Italy	53		
73 - 90	Module Part Number	32M x 64, -260	ASCII '13N32644JC'R'-260T'	31334E33323634344A43rr 2D323630542020	3, 4
		32M x 64, -360	ASCII '13N32644JC'R'-360T'	31334E33323634344A43rr 2D333630542020	
		32M x 72, -260	ASCII '13N32734JC'R'-260T'	31334E33323733344A43rr 2D323630542020	
		32M x 72, -360	ASCII '13N32734JC'R'-360T'	31334E33323733344A43rr 2D333630542020	
91 - 92	Module Revision Code	"R" plus ASCII blank	rr20	3, 4	
93 - 94	Module Manufacturing Date	Year/Week Code	yyww	5, 6	
95 - 98	Module Serial Number	Serial Number	ssssssss	7	
99 - 125	Reserved	Undefined	00		
126	Module Supports this Clock Frequency	100 MHz	64		
127	Attributes for Clock Frequency defined in byte 126	-260	CK0, CK1, CK2, CK3, CL3, CL2, concurrent AP	F7	
		-360	CK0, CK1, CK2, CK3, CL3, concurrent AP	F5	
128 - 255	Open for Customer Use	Undefined	00		

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## Absolute Maximum Ratings

Symbol	Parameter		Rating	Units	Notes
V <sub>DD</sub>	Power Supply Voltage		-0.3 to +4.6	V	1
V <sub>IN</sub>	Input Voltage	SDRAM Devices	-0.3 to V <sub>DD</sub> +0.3		
		Serial PD Device	-0.3 to +6.5		
V <sub>OUT</sub>	Output Voltage	SDRAM Devices	-0.3 to V <sub>DD</sub> +3.3		
		Serial PD Device	-0.3 to +6.5		
T <sub>A</sub>	Operating Temperature (ambient)		0 to +70	°C	1
T <sub>STG</sub>	Storage Temperature		-55 to +125	°C	1
P <sub>D</sub>	Power Dissipation	x64	6.5	W	1
		x72	7.3		
I <sub>OUT</sub>	Short Circuit Output Current		50	mA	1

1. Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Recommended DC Operating Conditions (T<sub>A</sub>= 0 to 70°C)

Symbol	Parameter	Rating			Units	Notes
		Min.	Typ.	Max.		
V <sub>DD</sub>	Supply Voltage	3.0	3.3	3.6	V	1
V <sub>IH</sub>	Input High Voltage	2.0	—	V <sub>DD</sub> + 0.3	V	1, 2
V <sub>IL</sub>	Input Low Voltage	-0.3	—	0.8	V	1, 3

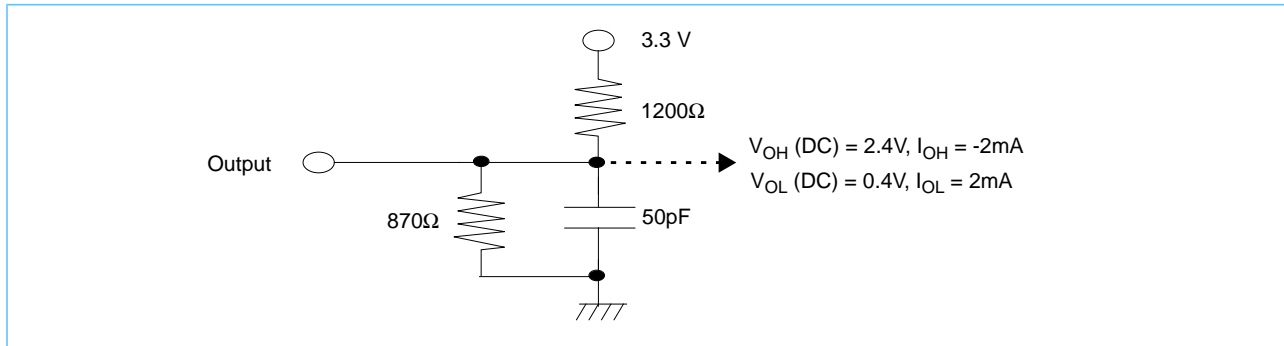
1. All voltages referenced to V<sub>SS</sub>.
2. V<sub>IH</sub>(max) = V<sub>DD</sub> + 1.2V for pulse width ≤ 5ns.
3. V<sub>IL</sub>(min) = V<sub>DD</sub> - 1.2V for pulse width ≤ 5ns.

## Capacitance (T<sub>A</sub>= 25°C, f=1MHz, V<sub>DD</sub>= 3.3V ± 0.3V)

Symbol	Parameter	Organization		Units
		x64 Max.	x72 Max.	
C <sub>I1</sub>	Input Capacitance (A0 - A9, A10/AP, A11, BA0, BA1, RAS, CAS, WE)	104	112	pF
C <sub>I2</sub>	Input Capacitance (CKE0 - CKE1)	54	58	pF
C <sub>I3</sub>	Input Capacitance ( $\overline{S}0$ - $\overline{S}3$ )	30	33	pF
C <sub>I4</sub>	Input Capacitance (CK0 - CK3)	40	40	pF
C <sub>I5</sub>	Input Capacitance (DQMB0 - DQMB7)	17	21	pF
C <sub>I6</sub>	Input Capacitance (SA0 - SA2, SCL, WP)	9	9	pF
C <sub>IO1</sub>	Input/Output Capacitance (DQ0 - DQ63, CB0 - CB7)	17	17	pF
C <sub>IO2</sub>	Input/Output Capacitance (SDA)	11	11	pF



## DC Output Load Circuit



## Output Characteristics $(T_A = 0 \text{ to } +70^\circ\text{C}, V_{DD} = 3.3V \pm 0.3V)$

Symbol	Parameter	x64		x72		Units	Notes	
		Min.	Max.	Min.	Max.			
$I_{I(L)}$	Input Leakage Current, any input $(0.0V \leq V_{IN} \leq V_{DD})$ , All Other Pins Not Under Test = 0V	RAS, CAS, WE, A0-A9, A10/AP, A11, BA0, BA1	-80	+80	-90	+90	$\mu\text{A}$	
		CK0, CK1	-20	+20	-25	+25		
		CK2, CK3	-20	+20	-20	+20		
		CKE0, CKE1	-40	+40	-45	+45		
		$\bar{S}0, \bar{S}1$	-20	+20	-25	+25		
		$\bar{S}2, \bar{S}3$	-20	+20	-20	+20		
		DQMB1, 5	-10	+10	-15	+15		
		DQMB0, 2, 3, 4, 5, 6, 7	-10	+10	-10	+10		
		DQ0 - 63	-10	+10	-10	+10		
		CB0 - 7	0	0	-10	+10		
		SA0, SA1, SA2, SCL, SDA	-10	+10	-10	+10		
		WP	-10	+50	-10	+50		
$I_{O(L)}$	Output Leakage Current ( $D_{OUT}$ is disabled, $0.0V \leq V_{OUT} \leq V_{DD}$ )	DQ0 - 63	-10	+10	-10	+10	$\mu\text{A}$	
		CB0 - 7	0	0	-10	+10		
		SDA	-10	+10	-10	+10		
$V_{OH}$	Output Level (LVTTTL) Output "H" Level Voltage ( $I_{OUT} = -2.0mA$ )	2.4	-	2.4	-	V	1	
$V_{OL}$	Output Level (LVTTTL) Output "L" Level Voltage ( $I_{OUT} = +2.0mA$ )	-	0.4	-	0.4			

1. See DC output load circuit.

**Operating, Standby, and Refresh Currents** ( $T_A = 0$  to  $+70^\circ\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 0.3\text{V}$ )

Parameter	Symbol	Test Condition	Speed/Organization		Units	Notes
			-260, -360/x64	-260, -360/x72		
Operating Current $t_{RC} = t_{RC}(\text{min})$ , $t_{CK} = \text{min}$ Active-Precharge command cycling without Burst operation	$I_{CC1}$	1 bank operation	960	1080	mA	1, 3, 4
Precharge Standby Current in Power Down Mode	$I_{CC2P}$	$\text{CKE0, CKE1} \leq V_{IL}(\text{max})$ , $t_{CK} = \text{min}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$	16	18	mA	2
	$I_{CC2PS}$	$\text{CKE0, CKE1} \leq V_{IL}(\text{max})$ , $t_{CK} = \text{Infinity}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$	16	18	mA	2
Precharge Standby Current in Non-Power Down Mode	$I_{CC2N}$	$\text{CKE0, CKE1} \geq V_{IH}(\text{min})$ , $t_{CK} = \text{min}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$	560	630	mA	2, 5
	$I_{CC2NS}$	$\text{CKE0, CKE1} \geq V_{IH}(\text{min})$ , $t_{CK} = \text{Infinity}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$	160	180	mA	2, 6
No Operating Current (Active state: 4 bank)	$I_{CC3N}$	$\text{CKE0, CKE1} \geq V_{IH}(\text{min})$ , $t_{CK} = \text{min}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$	640	720	mA	2, 5
	$I_{CC3P}$	$\text{CKE0, CKE1} \leq V_{IL}(\text{max})$ , $t_{CK} = \text{min}$ , $\overline{S0} - \overline{S3} = V_{IH}(\text{min})$ (Power Down Mode)	160	180	mA	2, 7
Burst Operating Current	$I_{CC4}$	$t_{CK} = \text{min}$ , Read/ Write command cycling, multiple banks active, gapless data, BL = 4	1040	1170	mA	1, 4, 8
Auto (CBR) Refresh Current	$I_{CC5}$	$t_{CK} = \text{min}$ , CBR command cycling	1800	2025	mA	1
Self Refresh Current	$I_{CC6}$	$\text{CKE0, CKE1} \leq 0.2\text{V}$	32	36	mA	2
Serial PD Device Standby Current	$I_{SB}$	$V_{IN} = \text{GND}$ or $V_{DD}$	30	30	$\mu\text{A}$	9
Serial PD Device Active Power Supply Current	$I_{CCA}$	SCL Clock Frequency = 100KHz	1	1	mA	10

1. The specified values are for one DIMM bank in the specified mode, and the other DIMM bank in Active Standby ( $I_{CC3N}$ ).
2. The specified values are for both DIMM banks operating in the specified mode.
3. These parameters depend on the cycle rate and are measured with the cycle determined by the minimum value of  $t_{CK}$  and  $t_{RC}$ . Input signals are changed up to three times during  $t_{RC}(\text{min})$ .
4. The specified values are obtained with the output open.
5. Input signals are changed once during three clock cycles.
6. Input signals are stable.
7. Active Standby current will be higher if clock suspend is entered during a Burst Read cycle (add 1mA per DQ).
8. Input signals are changed once during  $t_{CK}(\text{min})$ .
9.  $V_{DD} = 3.3\text{V}$ .
10. As follows:
  - Input pulse levels  $V_{DD} \times 0.1$  to  $V_{DD} \times 0.9$
  - Input and output timing levels  $V_{DD} \times 0.5$
  - Output load 1 TTL gate and  $CL=100\text{pF}$



## Clock and Clock Enable Parameters

Symbol	Parameter	-260		-360		Units	Notes
		Min.	Max.	Min.	Max.		
$t_{CK3}$	Clock Cycle Time, $\overline{CAS}$ Latency = 3	10	1000	10	1000	ns	
$t_{CK2}$	Clock Cycle Time, $\overline{CAS}$ Latency = 2	10	1000	15	1000	ns	1
$t_{AC3(A)}$	Clock Access Time, $\overline{CAS}$ Latency = 3	—	—	—	—	ns	2
$t_{AC2(A)}$	Clock Access Time, $\overline{CAS}$ Latency = 2	—	—	—	—	ns	2
$t_{AC3(B)}$	Clock Access Time, $\overline{CAS}$ Latency = 3	—	6	—	6	ns	3
$t_{AC2(B)}$	Clock Access Time, $\overline{CAS}$ Latency = 2	—	6	—	9	ns	3
$t_{CKH}$	Clock High Pulse Width	3	—	3	—	ns	4
$t_{CKL}$	Clock Low Pulse Width	3	—	3	—	ns	4
$t_{CES}$	Clock Enable Set-up Time	2	—	2	—	ns	
$t_{CEH}$	Clock Enable Hold Time	1	—	1	—	ns	
$t_{SB}$	Power down mode Entry Time	0	10	0	10	ns	
$t_T$	Transition Time (Rise and Fall)	0.5	10	0.5	10	ns	

1. For -360 sort, 66Mhz clock:  $\overline{CAS}$  Latency = 2.
2. Access time is measured at 1.4V. See AC Characteristics: notes: 1, 2, 3, 4, 5 and load circuit A.
3. Access time is measured at 1.4V. See AC Characteristics: notes: 1, 2, 3, 6, 7 and load circuit B.
4.  $t_{CKH}$  is the pulse width of CLK measured from the positive edge to the negative edge referenced to  $V_{IH}$  (min).  $t_{CKL}$  is the pulse width of CLK measured from the negative edge to the positive edge referenced to  $V_{IL}$  (max).

## Common Parameters

Symbol	Parameter	-260		-360		Units	Notes
		Min.	Max.	Min.	Max.		
$t_{CS}$	Command Setup Time	2	—	2	—	ns	
$t_{CH}$	Command Hold Time	1	—	1	—	ns	
$t_{AS}$	Address and Bank Select Set-up Time	2	—	2	—	ns	
$t_{AH}$	Address and Bank Select Hold Time	1	—	1	—	ns	
$t_{RCD}$	$\overline{RAS}$ to $\overline{CAS}$ Delay	20	—	20	—	ns	1
$t_{RC}$	Bank Cycle Time	70	—	70	—	ns	1
$t_{RAS}$	Active Command Period	50	100000	50	100000	ns	1
$t_{RP}$	Precharge Time	20	—	20	—	ns	1
$t_{RRD}$	Bank to Bank Delay Time	20	—	20	—	ns	1
$t_{CCD}$	$\overline{CAS}$ to $\overline{CAS}$ Delay Time	1	—	1	—	CLK	

1. These parameters account for the number of clock cycle and depend on the operating frequency of the clock, as follows:  
 the number of clock cycles = specified value of timing / clock period (count fractions as a whole number).



## Mode Register Set Cycle

Symbol	Parameter	-260		-360		Units	Notes
		Min.	Max.	Min.	Max.		
$t_{RSC}$	Mode Register Set Cycle Time	2	—	2	—	CLK	1

1. These parameters account for the number of clock cycle and depend on the operating frequency of the clock, as follows:  
the number of clock cycles = specified value of timing / clock period (count fractions as a whole number).

## Read Cycle

Symbol	Parameter	-260		-360		Units	Notes
		Min.	Max.	Min.	Max.		
$t_{OH}$	Data Out Hold Time	2.5	—	2.5	—	ns	
$t_{LZ}$	Data Out to Low Impedance Time	0	—	0	—	ns	
$t_{HZ3}$	Data Out to High Impedance Time	3	6	3	6	ns	1
$t_{HZ2}$	Data Out to High Impedance Time	3	6	3	8	ns	1
$t_{DQZ}$	DQM Data Out Disable Latency	2	—	2	—	CLK	

1. Referenced to the time at which the output achieves the open circuit condition, not to output voltage levels.

## Refresh Cycle

Symbol	Parameter	-260		-360		Units	Notes
		Min.	Max.	Min.	Max.		
$t_{REF}$	Refresh Period	—	64	—	64	ms	1
$t_{SREX}$	Self Refresh Exit Time	10		10		ns	

1. 4096 auto refresh cycles.

## Write Cycle

Symbol	Parameter	-260		-360		Units
		Min.	Max.	Min.	Max.	
$t_{DS}$	Data In Set-up Time	2	—	2	—	ns
$t_{DH}$	Data In Hold Time	1	—	1	—	ns
$t_{DPL}$	Data input to Precharge	10	—	10	—	ns
$t_{DQW}$	DQM Write Mask Latency	0	-	0	-	CLK



## Presence Detect Read and Write Cycle

Symbol	Parameter	Min	Max	Unit	Notes
$f_{SCL}$	SCL Clock Frequency		100	kHz	
$T_I$	Noise Suppression Time Constant at SCL, SDA Inputs		100	ns	
$t_{AA}$	SCL Low to SDA Data Out Valid	0.3	3.5	$\mu$ s	
$t_{BUF}$	Time the Bus Must Be Free before a New Transmission Can Start	4.7		$\mu$ s	
$t_{HD:STA}$	Start Condition Hold Time	4.0		$\mu$ s	
$t_{LOW}$	Clock Low Period	4.7		$\mu$ s	
$t_{HIGH}$	Clock High Period	4.0		$\mu$ s	
$t_{SU:STA}$	Start Condition Setup Time (for a Repeated Start Condition)	4.7		$\mu$ s	
$t_{HD:DAT}$	Data in Hold Time	0		$\mu$ s	
$t_{SU:DAT}$	Data in Setup Time	250		ns	
$t_r$	SDA and SCL Rise Time		1	$\mu$ s	
$t_f$	SDA and SCL Fall Time		300	ns	
$t_{SU:STO}$	Stop Condition Setup Time	4.7		$\mu$ s	
$t_{DH}$	Data Out Hold Time	300		ns	
$t_{WR}$	Write Cycle Time		15	ms	1

1. The Write cycle time ( $t_{WR}$ ) is the time from a valid stop condition of a write sequence to the end of the internal Erase/Program cycle. During the Write cycle, the bus interface circuits are disabled, SDA is allowed to remain high per the bus-level pull-up resistor, and the device does not respond to its slave address.



## Functional Description and Timing Diagrams

Refer to the IBM 128Mb Synchronous DRAM Die Revision A data sheet, document 33L8019, for the functional description and timing diagrams for SDRAM operation.

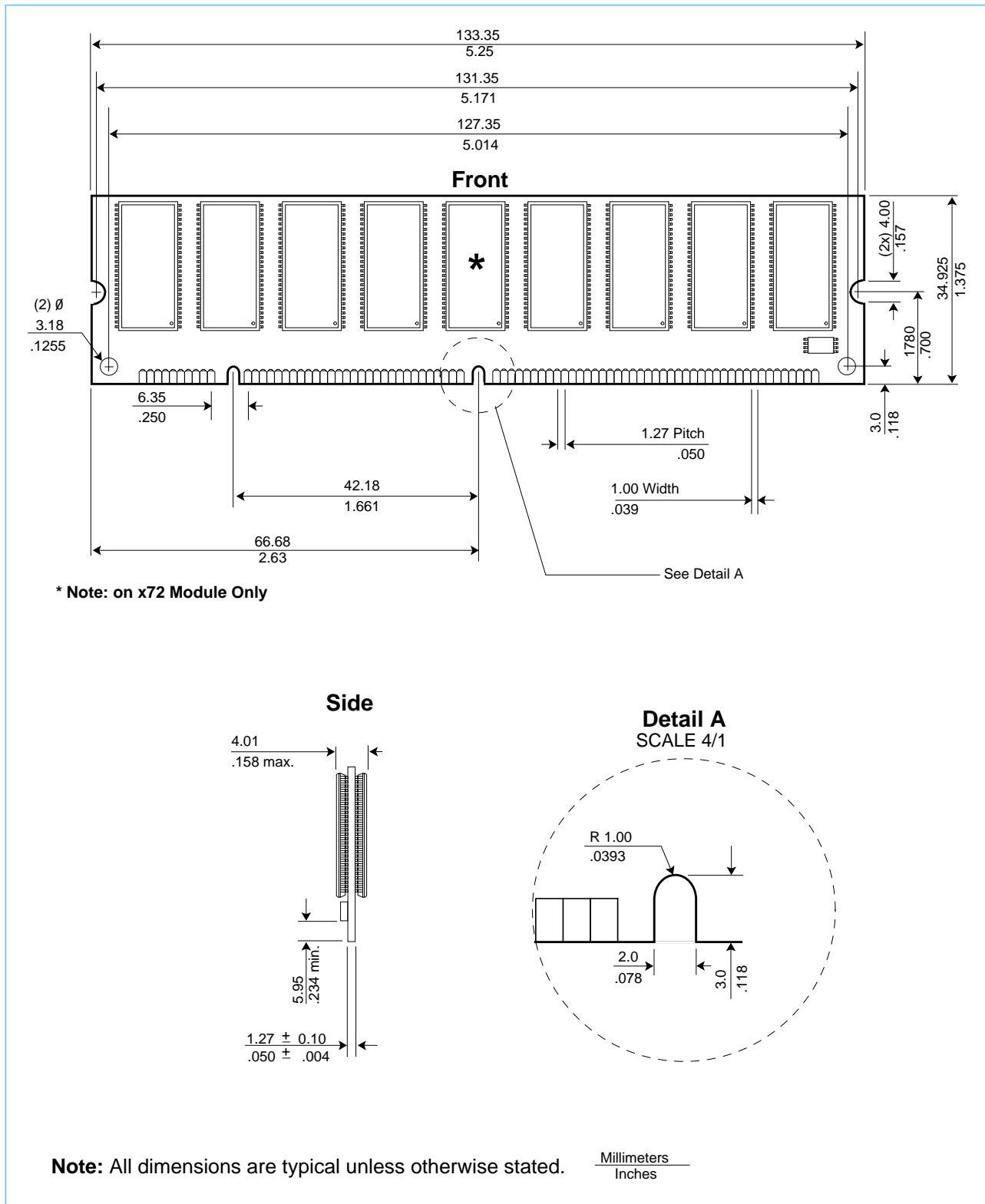
Refer to the IBM Application Notes *Serial Presence Detect on Memory DIMMs* and *SDRAM Presence Detect Definitions* for the Serial Presence Detect functional description and timings.

All AC timing information refers to the timings at the SDRAM devices.





## Layout Drawing





## Revision Log

Rev	Contents of Modification
7/99	Initial Release.
8/99	Removed Preliminary



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